

ABSTRACT OF THE DISCLOSURE

5 A plurality of semiconductor chips bent along
the outer circumferential surface of a cylindrical
substrate are mounted to the outer circumferential
surface of the substrate. The bumps of these
semiconductor chips are connected to connection pads
formed on the outer circumferential surface of the
substrate. By diminishing the curvature radius of the
bent semiconductor chips, the size of the semiconductor
10 module can be made smaller than the size of the chip.